SYSTEM AND METHOD FOR INSPECTING A WAFER

Abstract

An inspection system for inspecting a semiconductor wafer. The inspection system comprises an illumination setup for supplying broadband illumination. The broadband illumination can be of different contrasts, for example brightfield and darkfield broadband illumination. The inspection system further comprises a first image capture device and a second image capture device, each configured for receiving broadband illumination to capture images of the semiconductor wafer while the semiconductor wafer is in motion. The system comprises a number of tube lenses for enabling collimation of the broadband illumination. The system also comprises a stabilizing mechanism and an objective lens assembly. The system further comprises a thin line illumination emitter and a third image capture device for receiving thin line illumination to thereby capture three-dimensional images of the semiconductor wafer. The system comprises a reflector assembly for enabling the third image capture device to receive illumination reflected from the semiconductor wafer in multiple directions.

Figure 1